CLAIMS:

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1.	Α	device	comprising
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- a first and a second layer (11, 13) separated from each other; and
- nanosized filamentary material (10) grown between said first and said second layer (11, 13).

2. A device according to claim 1, wherein the size and shape of the nanosized filamentary material (10) is determined by the size and shape of the second layer (13).

- 3. A device according to claim 1, wherein the first and second layers (11, 13) are conductive.
 - 4. A device according to claim 3, further comprising:

 at least a bottom and a top contact (31, 32), said bottom contact (31) being

 connected to the first conductive layer (11) and said top contact (32) being connected to the

 second conductive layer (13).
 - 5. A device according to claim 1, wherein the device is an electronic device.
 - 6. A device according to claim 5, wherein the device is a sensor.
 - 7. An array comprising a plurality of devices according to claim 1.
 - 8. A method for manufacturing nanosized filamentary material (10), the method comprising:
- 25 providing a stack (14) comprising at least a first catalyst layer (12) which is catalytically active with respect to the growth of nanosized filamentary material (10) and which is provided in between at least a first layer (11) and second layer (13), said first and second layer (11, 13) being inert with respect to the growth of nanosized filamentary material (10);

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- growing nanosized filamentary material (10) in between said first and second layer (11, 13) whereby said first catalyst layer (12) is converted into a layer comprising the nanosized filamentary material (10).
- 5 9. A method according to claim 8, wherein growing nanosized filamentary material (10) in between said first and second layer (11, 13) is performed by a chemical vapor deposition (CVD) technique.
 - 10. A method according to claim 8, wherein providing a stack (14) comprises:
 providing said first layer (11),
 - providing said first catalyst layer (12) onto at least part of said first layer (11), and
 - providing said second layer (13) on top of at least part of said first catalyst layer (12).
- 11. A method according to claim 10, wherein providing said first catalyst layer (12) onto at least part of said first layer (11) is performed by depositing a metal layer on at least part of said first layer (11).
- 20 12. A method according to claim 10, wherein providing said second layer (13) on top of at least part of said first catalyst layer (12) is performed by depositing a conductive layer.